

wave generated inside the package; wherein

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an insulating joining material is arranged to join the main body of the package and the cover, a metallized electrode which is located above the signal electrodes and is not in contact with the signal electrodes and is not in contact with the insulating joining material, the metallized electrode being provided at a fixed location of the main body of the package, and the metallized electrode is arranged to be conductive to the grounding electrode.

11. A surface acoustic wave device comprising:

a surface acoustic wave element; and

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a package containing the surface acoustic wave element, the package made up of a main body of the package of an insulating material having a hollow space therein, a cover of an insulating material provided on the upper surface of the main body of the package and for closing the opening portion of the main body of the package, signal electrodes for transmitting a signal input from the outside of the package and a signal output from the surface acoustic wave element, and a grounding electrode for grounding an unwanted electromagnetic wave generated inside the package; wherein

the main body of the package and the cover are joined at bonding surfaces of the package and the cover by thermocompression bonding, a metallized electrode which is located above the signal electrodes and is not in contact with the signal electrodes and is not in contact with the bonding surfaces of the package and the cover, the metallized electrode being provided at a fixed location of the main body of the package, and the metallized electrode is arranged to be conductive to the grounding electrode.